Index

B, C, D, E
buck converter, 8–10
burst mode, 62–63, 84, 85
capacitor charging, 15, 260
cascade power stage, 225–229, 242–245, 247
charge pump, 168, 169, 171
recovery, 67
current-mode control, 37–45, 48, 51–53
Dielectric material, 133–139, 147, 154
dimensioning of LC-filter, 22–28
dimensioning of power stage, 13–28
experimental results, 67–69

F, H, I, L
fabrication process, 104, 119, 125, 131
figure of merit, 96
figure of merit of magnetic devices, 118
fined-grain voltage generation, 21
frequency modulation, 42, 49, 50, 62, 191, 211–212
fully integrated converter, 72, 204
High frequency switching, 134
hybrid serial input-output converter, 262–270
topologies, 282
hysteretic control, 224
identification of design parameters, 214
Inductive DC-DC converter, 213
integrated capacitors, 70, 71, 84, 87, 140–150
interposer, 128, 129, 229–231, 242, 243, 246, 247
layout, 133, 134, 146, 149, 150, 155, 161, 171, 190, 198, 200, 201, 227–229, 244
lifetime, 93, 128, 149–150, 160, 275, 278
loss mechanisms in dielectric, 222
models, 73–81

M, O, P
magnetic materials, 70, 95, 111–118, 122, 124, 126, 127
Micro-inductors, 96, 104–108, 111, 113, 118, 119, 121–123, 125, 126
micro-transformers, 126
microprocessor power supplies, 2
minimum voltage deviation, 2, 63–69
multi-level power stage, 23
multi-output switched-capacitor converter, 270–279
multi-phase buck converter, 256
multiphase switching converter, 207
on-chip capacitor, 190, 201
polarization, 135–136
power density, 93
principle of operation, 257
pulse skipping, 62–63
pulse-frequency modulation, 62, 191
S, T, V

SC DC-DC converter, 98
serial-parallel converter, 150, 152
sliding-mode control, 40–45, 59, 157, 161–174, 245
step-down converter, 264, 267
step-up converter, 10
switched-capacitor, 179

switching-frequency control, 162, 168, 169
thin-film materials, 127
trench capacitors, 207
V1 concept, 52–58
voltage regulator, 45, 98, 193, 202, 205, 206
voltage swing reduction, 281